

FEATURES

Fault and overvoltage protection up to ± 40 V

Signal paths open circuit with power off

Signal path resistance of R_{ON} with power on

44 V supply maximum ratings

Low on resistance: 62 Ω typical

± 1 nA maximum path current leakage @ $+25^\circ\text{C}$

Low R_{ON} match (5 Ω maximum)

Low power dissipation 0.8 μW typical

Latch-up proof construction

APPLICATIONS

ATE equipment

Sensitive measurement equipment

Hot insertion rack systems

GENERAL DESCRIPTION

The ADG467 is an octal channel protector. The channel protector is placed in series with the signal path. The channel protector protects sensitive components from voltage transience in the signal path regardless if the power supplies are present or not. For this reason, the channel protectors are ideal for use in applications where correct power sequencing cannot always be guaranteed (for example, hot insertion rack systems) to protect analog inputs. This is described further, and some example circuits are given in the Applications Information section.

Each channel protector has an independent operation and consists of an N-channel MOSFET, a P-channel MOSFET, and an N-channel MOSFET, connected in series. The channel protector behaves just like a series resistor during normal operation, that is, $(V_{SS} + 1.5 \text{ V}) < V_{IN} < (V_{DD} - 1.5 \text{ V})$. When a channel's analog input exceeds the power supplies (including V_{DD} and $V_{SS} = 0 \text{ V}$), one of the MOSFETs switches off, clamping the output to either $V_{SS} + 1.5 \text{ V}$ or $V_{DD} - 1.5 \text{ V}$. Circuitry and signal source protection is provided in the event of an overvoltage or power loss. The channel protectors can withstand overvoltage inputs from -40 V to $+40 \text{ V}$. See the Circuit Information section.

The ADG467 can operate off both bipolar and unipolar supplies. The channels are normally on when power is

FUNCTIONAL BLOCK DIAGRAM

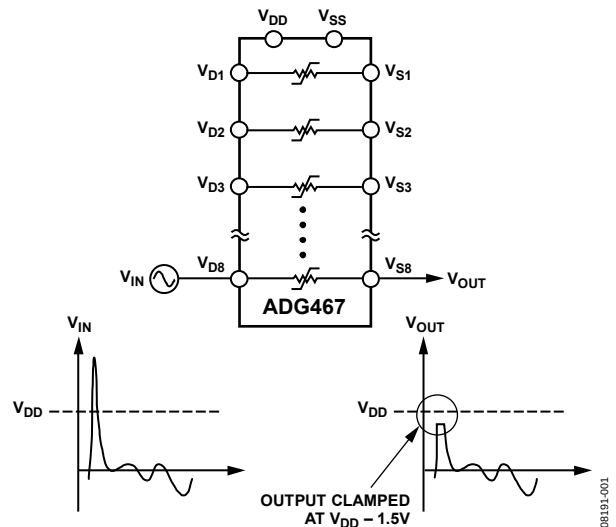


Figure 1.

connected and open circuit when power is disconnected. With power supplies of $\pm 15 \text{ V}$, the on resistance of the ADG467 is 62 Ω typical with a leakage current of $\pm 1 \text{ nA}$ maximum. When power is disconnected, the input leakage current is approximately $\pm 0.5 \text{ nA}$ typical.

The ADG467 is available in an 18-lead SOIC package and a 20-lead SSOP package.

PRODUCT HIGHLIGHTS

1. **Fault Protection.**
The ADG467 can withstand continuous voltage inputs from -40 V to $+40 \text{ V}$. When a fault occurs due to the power supplies being turned off or due to an overvoltage being applied to the ADG467, the output is clamped. When power is turned off, current is limited to the microampere level.
2. **Low Power Dissipation.**
3. **Low R_{ON} .** 62 Ω typical.
4. **Trench Isolation Latch-Up Proof Construction.**
A dielectric trench separates the p- and n-channel MOSFETs thereby preventing latch-up.

Rev. B

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REVISION HISTORY

2/11—Rev. A to Rev. B

Updated Format	Universal	Added Test Circuits Section and Figure 16 to Figure 20	8
Deleted ADG466	Universal	Changes to Overvoltage Protection Section and Figure 23	9
Changes to Features Section, General Description Section, Figure 1, and Product Highlights Section	1	Changes to Figure 24	10
Changes to Power Requirements, V_{DD}/V_{SS} Parameter, Table 1 ...	3	Change to Figure 26	11
Deleted 8-Lead DIP, SOIC, and μ SOIC Pin Configuration	3	Changes to Overvoltage and Power Supply Sequencing Protection Section and Figure 27	12
Deleted Figure 12; Renumbered Sequentially	5	Changes to High Voltage Surge Suppression Section and Figure 28	13
Changes to Figure 4 to Figure 6	6	Changes to Outline Dimensions	14
Added Figure 7; Renumbered Sequentially	6	Changes to Ordering Guide	15
Changes to Figure 11 to Figure 15	7		

SPECIFICATIONS

DUAL SUPPLY

$V_{DD} = +15\text{ V}$, $V_{SS} = -15\text{ V}$, $GND = 0\text{ V}$, unless otherwise noted.

Table 1.

Parameter	ADG467		Unit	Test Conditions/Comments
	+25°C	−40°C to +85°C		
FAULT PROTECTED CHANNEL				
Fault-Free Analog Signal Range	$V_{SS} + 1.5$ $V_{DD} - 1.5$ $V_{SS} + 1.7$ $V_{DD} - 1.7$		V typ V typ V typ V typ	Output open circuit Output loaded, 1 mA
R _{ON}	62	80 95	Ω typ Ω max	−10 V ≤ V _{Sx} ≤ +10 V, I _{Sx} = 1 mA
R _{ON} Flatness		6	Ω max	−5 V ≤ V _{Sx} ≤ +5 V
R _{ON} Match between Channels	5	6	Ω max	V _{Sx} = ±10 V, I _{Sx} = 1 mA
LEAKAGE CURRENTS				
Channel Output Leakage, I _{S(ON)} (Without Fault Condition)	±0.04 ±1	±0.2 ±5	nA typ nA max	V _{Sx} = V _{Dx} = ±10 V
Channel Input Leakage, I _{D(ON)} (with Fault Condition)	±0.2 ±2	±0.4 ±5	nA typ nA max	V _{Sx} = ±25 V V _{Dx} = open circuit
Channel Input Leakage, I _{D(OFF)} (with Power Off and Fault)	±0.5 ±2	±2 ±10	nA typ nA max	V _{DD} = 0 V, V _{SS} = 0 V V _{Sx} = ±35 V V _{Dx} = open circuit
Channel Input Leakage, I _{D(OFF)} (with Power Off and Output Short Circuit)	±0.006 ±0.015	±0.16 ±0.5	μA typ μA max	V _{DD} = 0 V, V _{SS} = 0 V V _{Sx} = ±35 V, V _{Dx} = 0 V
POWER REQUIREMENTS				
I _{DD}	±0.05 ±0.5	±8	μA typ μA max	
I _{SS}	±0.05 ±0.5	±8	μA typ μA max	
V _{DD} /V _{SS}		±4.5/±20	V min/max	

ABSOLUTE MAXIMUM RATINGS

$T_A = +25^\circ\text{C}$, unless otherwise noted.

Table 2.

Parameter	Rating
V_{DD} to V_{SS}	+44 V
V_{SX} , V_{DX} , Analog Input Overvoltage with Power On ¹	$V_{SS} - 20\text{ V}$ to $V_{DD} + 20\text{ V}$
V_{SX} , V_{DX} , Analog Input Overvoltage with Power Off ¹	-40 V to +40 V
Continuous Current, V_{SX} , V_{DX}	20 mA
Peak Current, V_{SX} , V_{DX} (Pulsed at 1 ms, 10% Duty Cycle Maximum)	40 mA
Operating Temperature Range Industrial (B Version)	-40°C to +85°C
Storage Temperature Range	-65°C to +125°C
Junction Temperature	+150°C
SOIC Package	
θ_{JA} , Thermal Impedance	160°C/W
Lead Temperature, Soldering	
Vapor Phase (60 sec)	+215°C
Infrared (15 sec)	+220°C
SSOP Package	
θ_{JA} , Thermal Impedance	130°C/W
Lead Temperature, Soldering	
Vapor Phase (60 sec)	+215°C
Infrared (15 sec)	+220°C

¹ Overvoltages at V_{SX} or V_{DX} are clamped by the channel protector; see the Circuit Information section.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION



ESD (electrostatic discharge) sensitive device.

Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

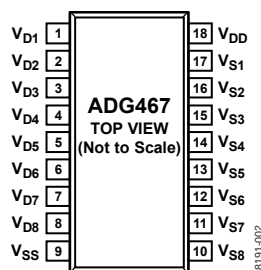


Figure 2. 18-Lead SOIC Pin Configuration

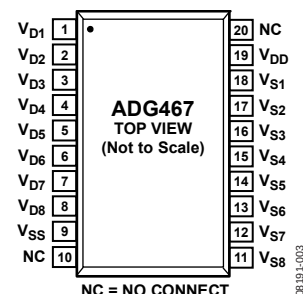


Figure 3. 20-Lead SSOP Pin Configuration

Table 3. Pin Function Descriptions

Pin No.		Mnemonic	Description
SOIC	SSOP		
1	1	V_{D1}	Drain Terminal 1. This pin can be an input or an output.
2	2	V_{D2}	Drain Terminal 2. This pin can be an input or an output.
3	3	V_{D3}	Drain Terminal 3. This pin can be an input or an output.
4	4	V_{D4}	Drain Terminal 4. This pin can be an input or an output.
5	5	V_{D5}	Drain Terminal 5. This pin can be an input or an output.
6	6	V_{D6}	Drain Terminal 6. This pin can be an input or an output.
7	7	V_{D7}	Drain Terminal 7. This pin can be an input or an output.
8	8	V_{D8}	Drain Terminal 8. This pin can be an input or an output.
9	9	V_{SS}	Most Negative Power Supply Potential. In single-supply applications, this pin can be connected to ground.
N/A	10	NC	No Connect.
10	11	V_{S8}	Source Terminal 1. This pin can be an input or an output.
11	12	V_{S7}	Source Terminal 2. This pin can be an input or an output.
12	13	V_{S6}	Source Terminal 3. This pin can be an input or an output.
13	14	V_{S5}	Source Terminal 4. This pin can be an input or an output.
14	15	V_{S4}	Source Terminal 5. This pin can be an input or an output.
15	16	V_{S3}	Source Terminal 6. This pin can be an input or an output.
16	17	V_{S2}	Source Terminal 7. This pin can be an input or an output.
17	18	V_{S1}	Source Terminal 8. This pin can be an input or an output.
18	19	V_{DD}	Most Positive Power Supply Potential.
N/A	20	NC	No Connect. Do not connect to this pin.

TYPICAL PERFORMANCE CHARACTERISTICS

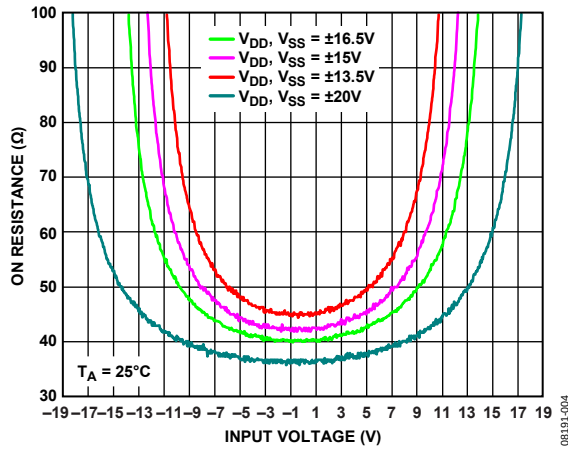


Figure 4. On Resistance as a Function of V_{DD} and V_{SX} (Input Voltage), Dual Supply

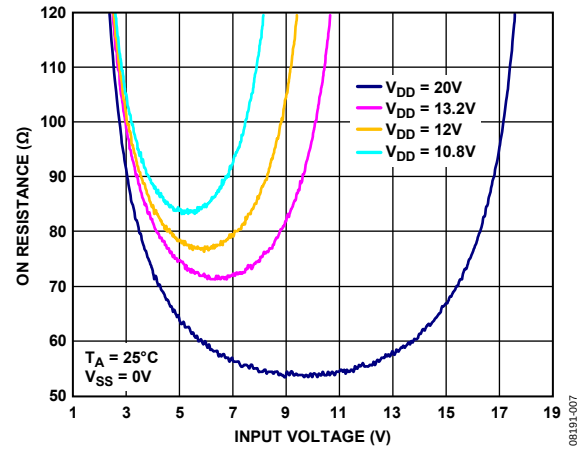


Figure 7. On Resistance as a Function of V_{DD} and V_{SX} (Input Voltage), Single Supply

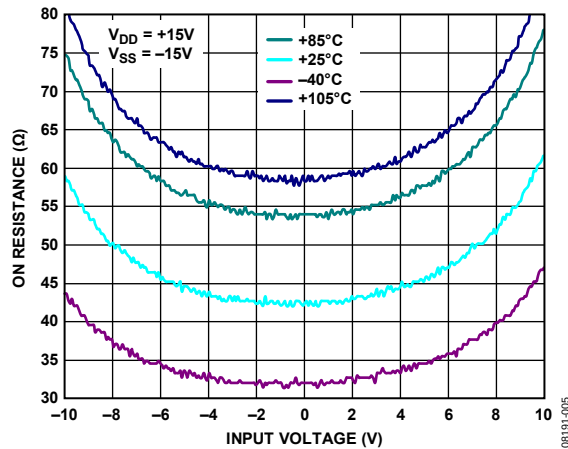


Figure 5. On Resistance as a Function of Temperature and V_{SX} (Input Voltage)

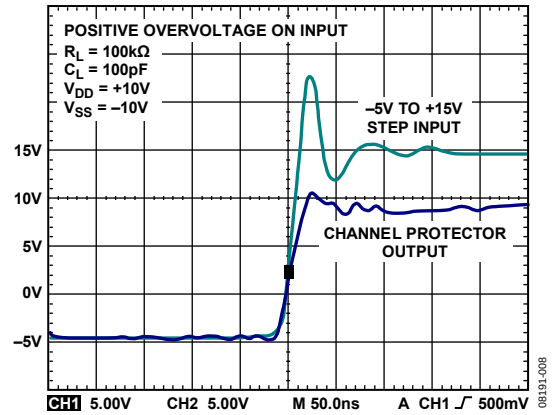


Figure 8. Positive Overvoltage Transience Response

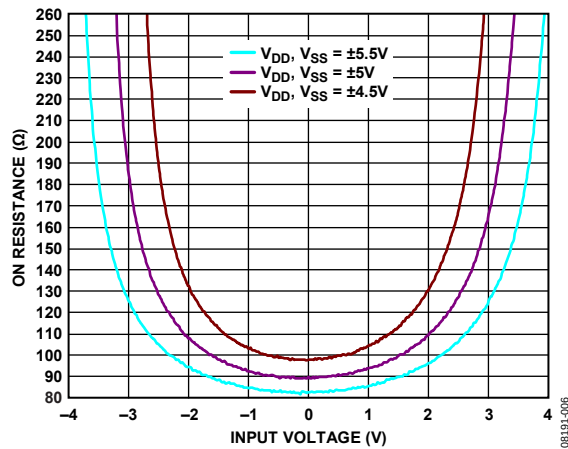


Figure 6. On Resistance as a Function of V_{DD} and V_{SX} (Input Voltage), 5 V Dual Supply

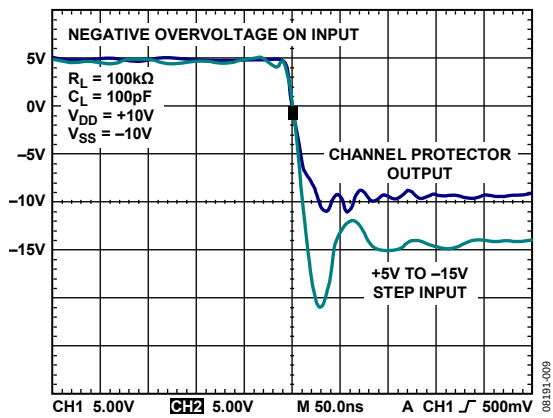


Figure 9. Negative Overvoltage Transience Response

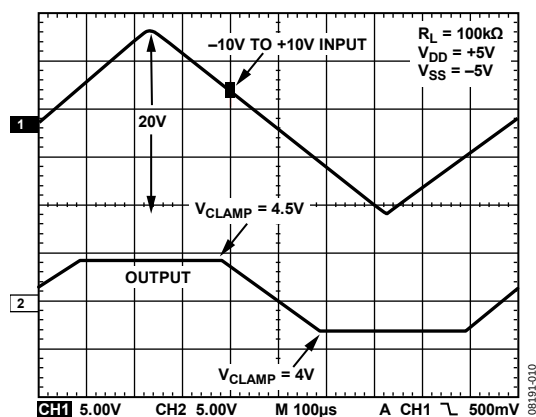


Figure 10. Overvoltage Ramp

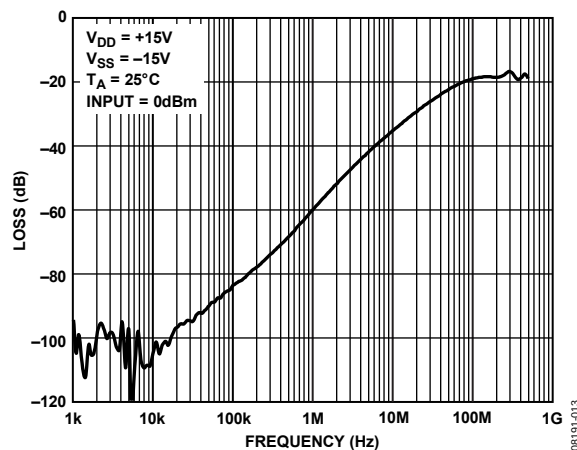


Figure 13. Crosstalk Between Adjacent Channels

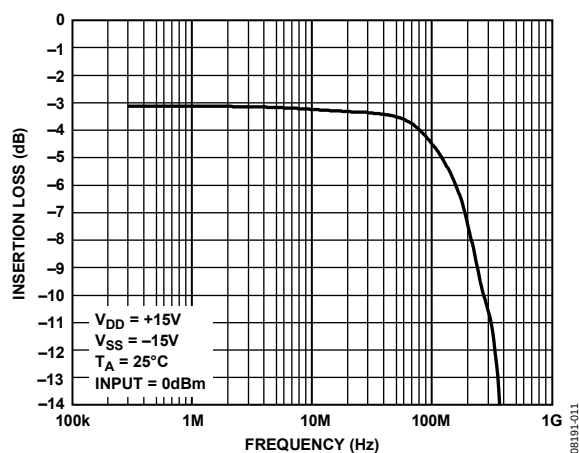


Figure 11. Frequency Response (Magnitude)

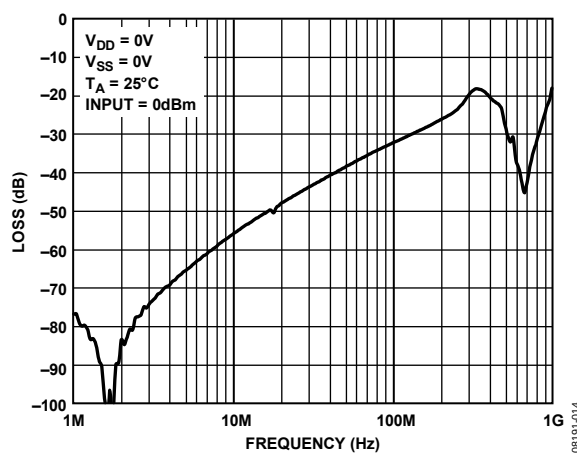


Figure 14. Off Isolation

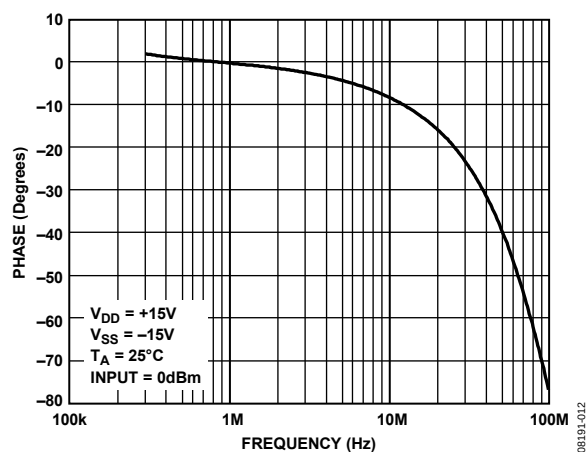


Figure 12. Frequency Response (Phase)

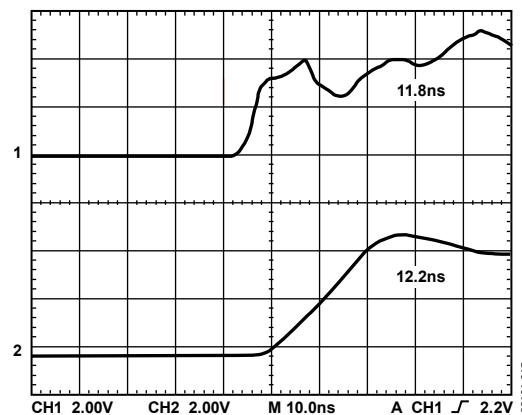


Figure 15. Propagation Delay

TEST CIRCUITS

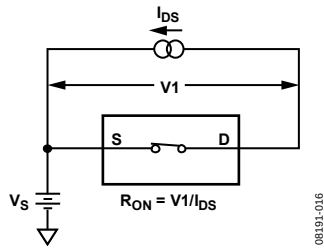


Figure 16. On Resistance

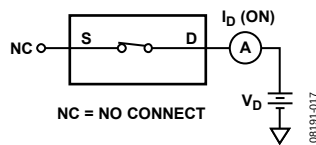


Figure 17. On Leakage

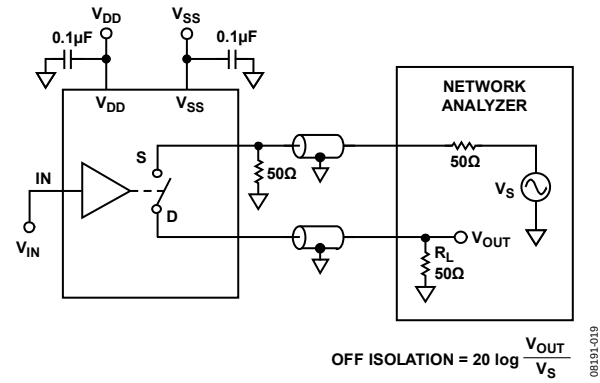


Figure 19. Off Isolation

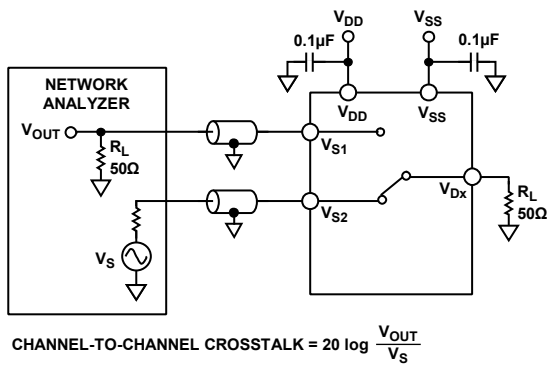


Figure 18. Channel-to-Channel Crosstalk

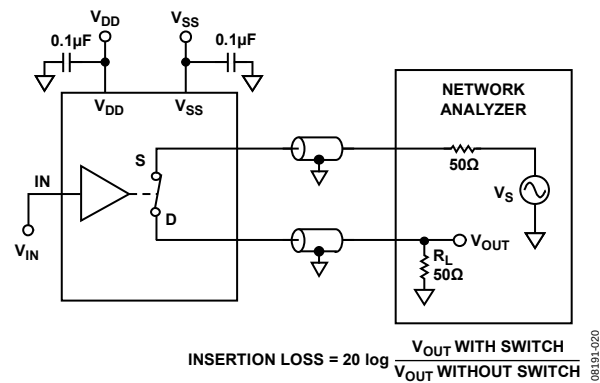


Figure 20. Bandwidth

When a negative overvoltage is applied to the channel protector circuit, the PMOS transistor enters a saturated mode of operation as the drain voltage exceeds $V_{SS} - V_{TP}$ (see Figure 24). As in the case of the positive overvoltage, the other MOS devices are nonsaturated.

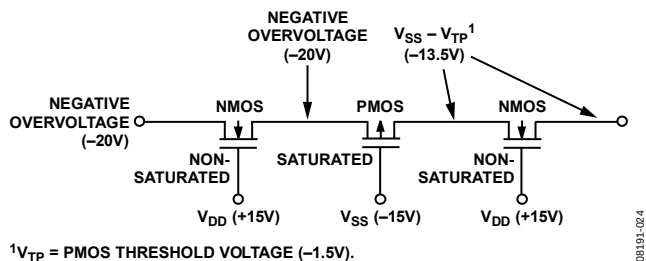


Figure 24. Negative Overvoltage on the Channel Protector

The channel protector is also functional when the supply rails are down (for example, power failure) or momentarily unconnected (for example, rack system). This is where the channel protector has an advantage over more conventional protection methods such as diode clamping (see the Applications Information section). When V_{DD} and V_{SS} equal 0 V, all transistors are off and the current is limited to subnano-ampere levels (see Figure 25).

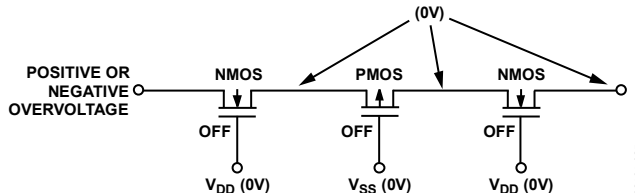


Figure 25. Channel Protector Supplies Equal to 0 V

TRENCH ISOLATION

The MOS devices that make up the channel protector are isolated from each other by an oxide layer (trench) (see Figure 26). When the NMOS and PMOS devices are not electrically isolated from each other, parasitic junctions between CMOS transistors may cause latch-up. Latch-up is caused when P-N junctions that are normally reverse biased become forward biased, causing large currents to flow, which can be destructive.

CMOS devices are normally isolated from each other by junction isolation. In junction isolation, the N and P wells of the CMOS transistors form a diode that is reverse biased under normal operation. However, during overvoltage conditions, this diode becomes forward biased. A silicon-controlled rectifier (SCR) type circuit is formed by the two transistors causing a significant amplification of the current that, in turn, leads to latch-up. With trench isolation, this diode is removed; the result is a latch-up-proof circuit.

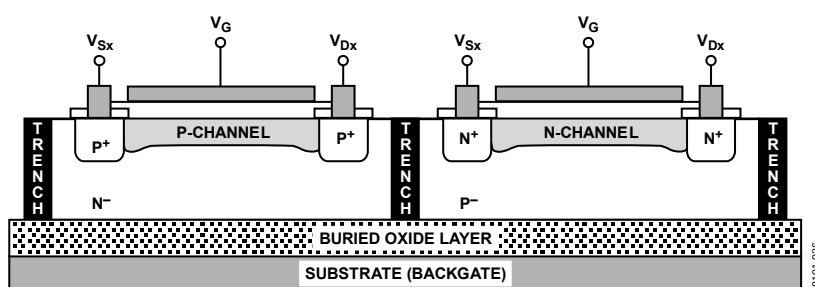


Figure 26. Trench Isolation

08191-026

APPLICATIONS INFORMATION

OVERVOLTAGE AND POWER SUPPLY SEQUENCING PROTECTION

The ADG467 is ideal for use in applications where input overvoltage protection is required and correct power supply sequencing cannot always be guaranteed. The overvoltage protection ensures that the output voltage of the channel protector does not exceed the threshold voltages set by the supplies (see the Circuit Information section) when there is an overvoltage on the input. When the input voltage does not exceed these threshold voltages, the channel protector behaves like a series resistor (62 Ω typical). The resistance of the channel protector does vary slightly with operating conditions (see the Typical Performance Characteristics section).

The power sequencing protection is provided by the channel protector, which becomes a high resistance device when the supplies to the channel protector are not connected. Under this condition, all transistors in the channel protector are off and the only currents that flow are leakage currents, which are at the microampere level.

Figure 27 shows a typical application that requires overvoltage and power supply sequencing protection. The application shows a hot insertion rack system. This involves plugging a circuit board or module into a live rack via an edge connector. In this type of application, it is not possible to guarantee correct power supply sequencing. Correct power supply sequencing means that the power supplies should be connected before any external signals. Incorrect power sequencing can cause a CMOS device to latch up. This is true of most CMOS devices regardless of the functionality. RC networks are used on the supplies of the channel protector (see Figure 27) to ensure that the rest of the circuitry is powered up before the channel protectors. In this way, the outputs of the channel protectors are clamped well below V_{DD} and V_{SS} until the capacitors are charged. The diodes ensure that the supplies on the channel protector never exceed the supply rails of the board when it is being disconnected. This ensures that signals on the inputs of the CMOS devices never exceed the supplies.

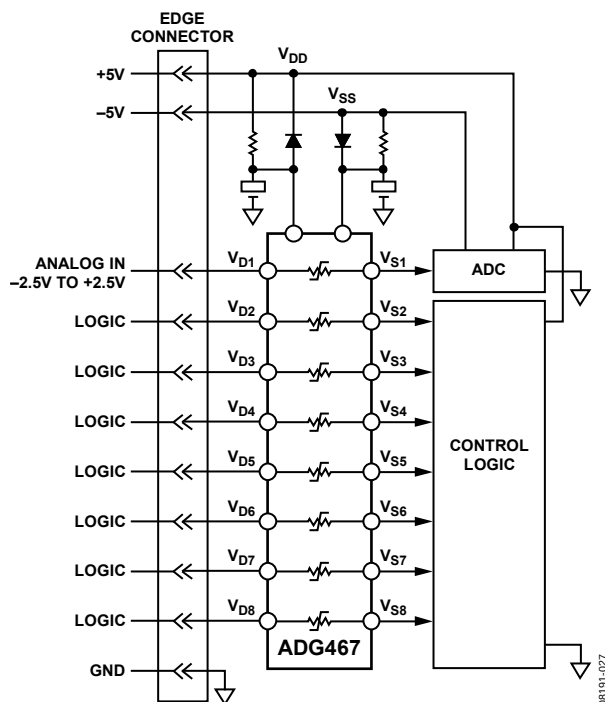


Figure 27. Overvoltage and Power Supply Sequencing Protection

HIGH VOLTAGE SURGE SUPPRESSION

The ADG467 is not intended for use in high voltage applications like surge suppression. The ADG467 has breakdown voltages in excess of $V_{SS} - 20\text{ V}$ and $V_{DD} + 20\text{ V}$ on the inputs when the power supplies are connected. When the power supplies are disconnected, the breakdown voltages on the input of the channel protector are $\pm 40\text{ V}$. In applications where inputs are likely to be subject to overvoltages exceeding the breakdown voltages specified for the channel protectors, transient voltage suppressors (TVSs) should be used. These devices are commonly used to protect vulnerable circuits from electric overstress such as that caused by electrostatic discharge, inductive load switching, and induced lightning. However, TVSs can have a substantial standby (leakage) current ($300\text{ }\mu\text{A}$ typical) at the reverse standoff voltage. The reverse stand-off

voltage of a TVS is the normal peak operating voltage of the circuit. Also, a TVS offers no protection against latch-up of sensitive CMOS devices when the power supplies are off. The ideal solution is to use a channel protector in conjunction with a TVS to provide the optimal leakage current specification and circuit protection.

Figure 28 shows an input protection scheme that uses both a TVS and a channel protector. The TVS is selected with a reverse standoff voltage that is much greater than the operating voltage of the circuit (TVSs with higher breakdown voltages tend to have better standby leakage current specifications) but is inside the breakdown voltage of the channel protector. This circuit protects the circuitry regardless of whether the power supplies are present.

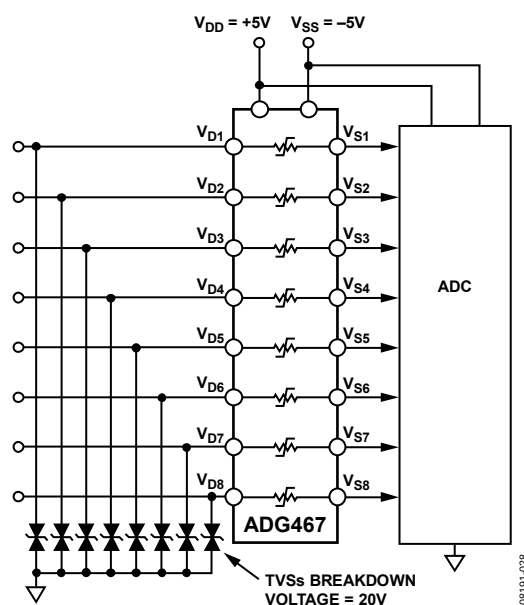
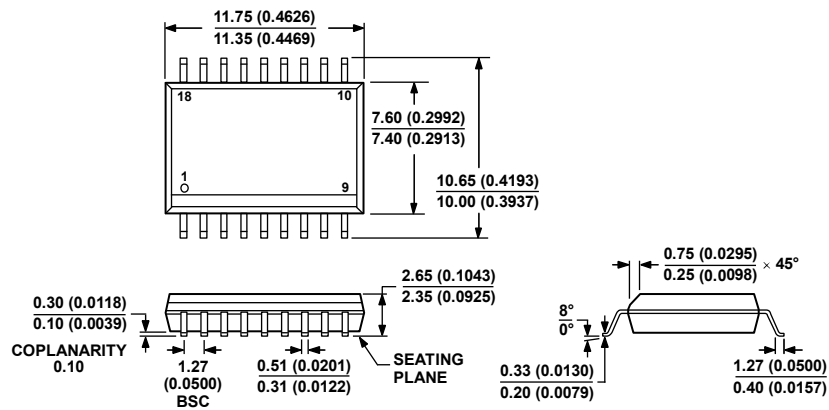


Figure 28. High Voltage Protection

OUTLINE DIMENSIONS

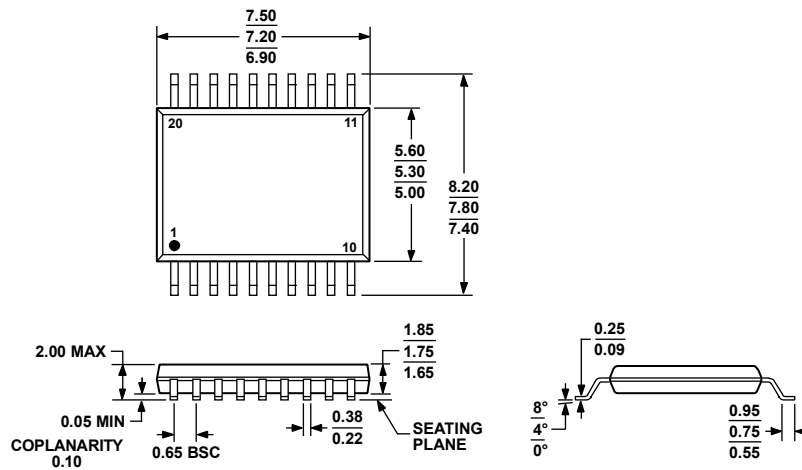


COMPLIANT TO JEDEC STANDARDS MS-013-AB
CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
(IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

Figure 29. 18-Lead Standard Small Outline Package [SOIC_W]
Wide Body (RW-18)

Dimensions shown in millimeters and (inches)

060706-A



COMPLIANT TO JEDEC STANDARDS MO-150-AE

Figure 30. 20-Lead Shrink Small Outline Package [SSOP]
(RS-20)

Dimensions shown in millimeters

060106-A

ORDERING GUIDE

Model¹	Temperature Range	Package Description	Package Option
ADG467BR	–40°C to +85°C	18-Lead Standard Small Outline Package [SOIC_W]	RW-18
ADG467BR-REEL	–40°C to +85°C	18-Lead Standard Small Outline Package [SOIC_W]	RW-18
ADG467BR-REEL7	–40°C to +85°C	18-Lead Standard Small Outline Package [SOIC_W]	RW-18
ADG467BRZ	–40°C to +85°C	18-Lead Standard Small Outline Package [SOIC_W]	RW-18
ADG467BRZ-REEL	–40°C to +85°C	18-Lead Standard Small Outline Package [SOIC_W]	RW-18
ADG467BRZ-REEL7	–40°C to +85°C	18-Lead Standard Small Outline Package [SOIC_W]	RW-18
ADG467BRS	–40°C to +85°C	20-Lead Shrink Small Outline Package [SSOP]	RS-20
ADG467BRS-REEL	–40°C to +85°C	20-Lead Shrink Small Outline Package [SSOP]	RS-20
ADG467BRSZ	–40°C to +85°C	20-Lead Shrink Small Outline Package [SSOP]	RS-20
ADG467BRSZ-REEL	–40°C to +85°C	20-Lead Shrink Small Outline Package [SSOP]	RS-20

¹ Z = RoHS Compliant Part.

ADG467

NOTES